

PCN Number:	20200331001.1	PCN Date:	April 1, 2020
Title:	Qualification of MIHO8 as an additional Fab site option for select devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	July 2, 2020	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process	
<input checked="" type="checkbox"/> Wafer Fab Site	<input checked="" type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Wafer Fab Process	
	<input type="checkbox"/> Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its MIHO8 fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Site	Process	Wafer Diameter
RFAB	LBC7	300 mm	MIHO8	LBC7	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current:

Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson

New Fab Site:

New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki

Sample product shipping label (not actual product label)

Product Affected:

BQ24780SRUYR	SN2850RUYR	SN2867RUYR	SN2867RUYT
BQ24780SRUYT	SN2850RUYT		

Qualification Report

Approve Date 27-Mar-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ24780SRUY	QBS Product Reference: BQ24780SRUY	QBS Process Reference: TPS62110RSA	QBS Package Reference: 430F2132IRHBR	QBS Package Reference: TPS51285BRUKR
HTOL	Life Test, 140C	480 Hours	-	-	3/231/0	-	-
ELFR	Early Life Failure Rate, 140C	48 Hours	-	-	3/1881/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0	-	-
AC	Autoclave 121C	96 Hours	-	1/77/0	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	1/77/0	3/231/0	3/231/0	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	-
CDM	ESD - CDM	1500 V	1/3/0	-	-	-	-
HBM	ESD - HBM	4000 V	1/3/0	-	-	-	-
LU	Latch-up	(per JESD78)	1/6/0	-	3/15/0	-	-

- QBS: Qual By Similarity

- Qual Device BQ24780SRUY is qualified at LEVEL 2-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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